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(21)Application number : **08-273954**(71)Applicant : **DAIWA KASEI KENKYUSHO:KK  
ISHIHARA CHEM CO LTD**(22)Date of filing : **26.09.1996**(72)Inventor : **OBATA KEIGO  
KONDO TETSUYA  
AOKI KAZUHIRO  
NAWAFUNE HIDEKI**

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**(54) ELECTRIC ELECTRONIC CIRCUIT PARTS****(57)Abstract:**

PROBLEM TO BE SOLVED: To join tin-silver alloy solder with excellent solderability, at the time of joining electric-electronic circuit parts with pollution-free tin-silver alloy solder, on the joint, by forming tin-silver alloy series electroplating having a specified compsn. to a specified thickness.

SOLUTION: At the time of soldering electric-electronic circuit parts with a safe tin-silver alloy series brazing filler metal without using a tin-lead series brazing filler metal contg. harmful lead, as coating for improving the solderability of the part to be soldered, mirror finished glossy tin-silver alloy coating contg. 0.1 to 10% silver is formed to a thickness of 1 to 100 $\mu$ m by electroplating. This tin-silver alloy plating coating is excellent in glossiness, is smooth and is excellent in solderability by the thin-silver alloy brazing filler metal and, since it contains no cyanogen, soldering free from problems of environment, hygiene and pollution similar to the case of solder by a tin-silver alloy brazing filler metal is made possible.

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3. In the drawings, any words are not translated.

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**CLAIMS**

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[Claim(s)]

[Claim 1] The electrical and electric equipment and electronic-circuitry parts with which the silver content in a coat is characterized by giving the tin-silver-alloy plating coat with the gloss whose coat thickness is 0.1-100 micrometers at 0.1% - 10% from the tin-silver-alloy electroplating bath of non-cyanogen.

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[Translation done.]